

Surface Mount PIN Diode Limiters

MLM2060-300 & MLM2060-301

Series Datasheet



Features

- Surface Mount Limiter in Compact Outline:
8mm L x 5mm W x 2.5 mm H
- Incorporates PIN Limiter Diodes, D.C. Blocks & D.C. Return
- Higher Average Power Handling than Plastic (100 W Peak Power)
- Lower Insertion Loss (0.85 dB) &
Lower Flat Leakage Power (19 dBm)
- RoHS Compliant



Description

The MLM2060-300 and MLM2060-301 Series of Surface Mount Silicon PIN Diode Limiters is manufactured using Aeroflex-Metelics proven hybrid manufacturing process incorporating PIN Diodes and passive devices integrated within a ceramic substrate. This low profile, compact, surface mount component, (8mm L x 5mm W x 2.5 mm H) offers superior low and high signal performance to comparable MMIC devices in QFN packages. The Limiter Modules are designed to optimize small signal insertion loss, (N.F.) and high signal flat leakage performance in a compact, surface mount package. The MLM2060-300 has Shunt PIN Limiter Diodes and a Shunt Coil with no D.C. Blocks, whereas the MLM2060-301 incorporates Shunt PIN Limiters Diodes, a Shunt Coil, and D.C. Blocks for versatility of design preference.

Using PIN Diodes with lower thermal resistance ($< 40 \text{ }^{\circ}\text{C/W}$), RF C.W. incident power levels of +36 dBm and RF peak incident power levels of + 50 dBm @ 1 μS RF pulse width, 0.001 duty cycle are very achievable in broadband Limiter Applications. The lower PIN Diode series resistance, ($< 1.5 \text{ } \Omega$), coupled with the smaller minority carrier lifetime, ($< 20 \text{ ns}$), provides lower flat leakage power ($< + 20 \text{ dBm}$) and lower spike leakage energy ($< 0.1 \text{ Ergs}$) for superior LNA protection.

Applications

These MLM2060-300 and MLM2060-301 Limiter Series are ideal for 2 to 6 GHz Radar, IED, and WiMax applications, requiring high volume, surface mount, solder re-flow manufacturing. These products are durable, reliable, and capable of meeting all military, commercial, and industrial environments. The devices are fully RoHS compliant and are available in tube or tape-reel.

Environmental Capabilities

The MLM2060-300 and MLM2060-301 Limiter Series is capable of meeting the environmental requirements of MIL-STD-750, MIL-STD-202, and MIL-STD-883.

ESD Rating

PIN Diodes are susceptible to ESD conditions as with all semiconductors. The ESD rating for these devices is Class 0, HBM.



MLM2060-300 & MLM2060-301 Electrical Specifications @ $Z_0 = 50 \Omega$, $T_A = +25^\circ\text{C}$ (Unless Otherwise Defined)

| Parameter | Symbol | Units | Test Conditions | Minimum Value | Typical Value | Maximum Value |
|-------------------------|---------------|----------|---|---------------|---------------|---------------|
| Frequency | F | GHz | Swept Frequency | | 2 - 6 | |
| Insertion Loss | I_L | dB | Swept Frequency $P_o = 0 \text{ dBm}$ | | -0.85 | -1.1 |
| Return Loss | R_L | dB | Swept Frequency $P_o = 0 \text{ dBm}$ | -13 | -14 | |
| Input Compression Power | P1dB | dBm | Swept Frequency | +7 | +8 | +10 |
| 2nd Harmonic | $2F_o$ | dBc | $P_o = 0 \text{ dBm}$ F = 4 GHz | 45 | 50 | |
| Peak Incident Power | $P_{inc(Pk)}$ | dBm | RF Pulse Width = 1 μ S, 0.001 duty | | +50 | +51 |
| C.W. Incident Power | $P_{inc(CW)}$ | dBm | Swept Frequency | | +35 | +36 |
| Flat Leakage Power | P_f | dBm | +50 dBm, RF Pulse Width = 1 μ S, 0.001 duty | | +18 | +20 |
| Spike Leakage Energy | E_s | Ergs | +50 dBm, RF Pulse Width = 1 μ S, 0.001 duty | | 0.1 | 0.2 |
| Recovery Time | T_r | η S | (50% Trailing RF Pulse – 1dB IL) | | 100 | 150 |

Part Number Ordering Information:

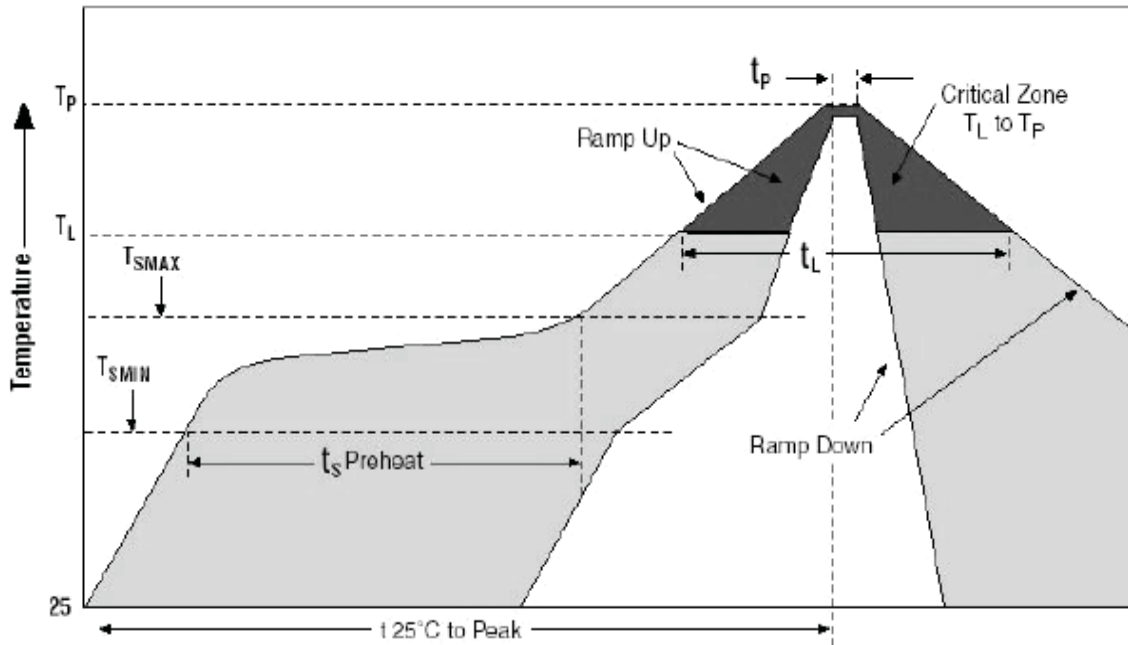
| Part Number | Packaging |
|---------------|-----------|
| MLM2060-300-T | Tube |
| MLM2060-300-R | Tape-Reel |
| MLM2060-301-T | Tube |
| MLM2060-301-R | Tape-Reel |

Assembly Instructions

The MLM2060-300 and MLM2060-301 Limiter Series is capable of being placed onto circuit boards with pick and place manufacturing equipment from tube, tape-reel, or wafflepack dispensing. The devices are attached to the circuit using conventional solder re-flow or wave soldering procedures with RoHS type or Sn 63 / Pb 37 type solders.

| Profile Feature | Sn-Pb Eutectic Assembly | Pb-Free Assembly |
|--|----------------------------------|----------------------------------|
| Average ramp-up rate (T_L to T_P) | 3°C/second maximum | 3°C/second maximum |
| Preheat - Temperature Minimum (T_{SMIN}) - Temperature Maximum (T_{SMAX}) - Time (Minimum to maximum) (t_g) | 100°C 150°C 60-120 seconds | 150°C 200°C 60-180 seconds |
| T_{SMAX} to T_L - Ramp-up Rate | | 3°C/second maximum |
| Time Maintained above: - Temperature (T_L) - Time (t_L) | 183°C 60-150 seconds | 217°C 60-150 seconds |
| Peak Temperature (T_P) | 225 +0 / -5°C | 245 +0/-5°C |
| Time within 5°C of actual Peak Temperature (T_P) | 10-30 seconds | 20-40 seconds |
| Ramp-down Rate | 6°C/second maximum | 6°C/second maximum |
| Time 25°C to Peak Temperature | 6 minutes maximum | 8 minutes maximum |

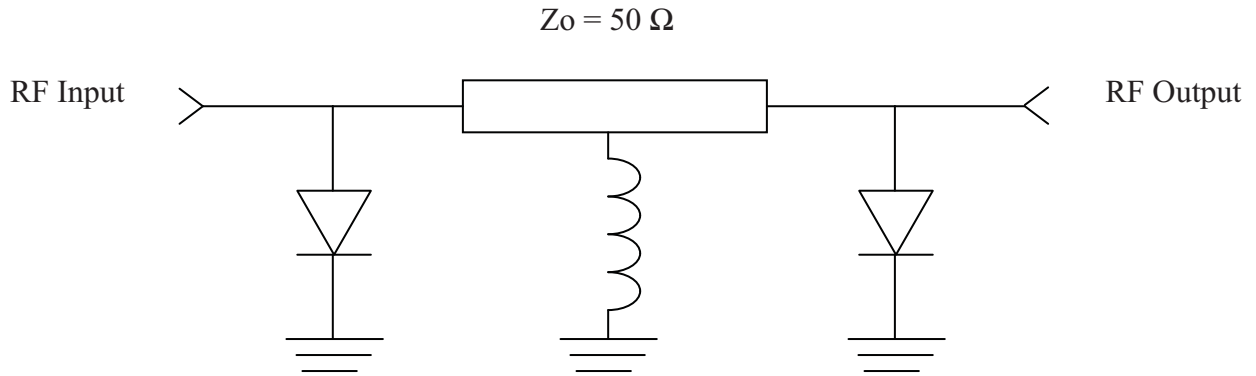
Graph 1: Solder Re-Flow Time-Temperature Function



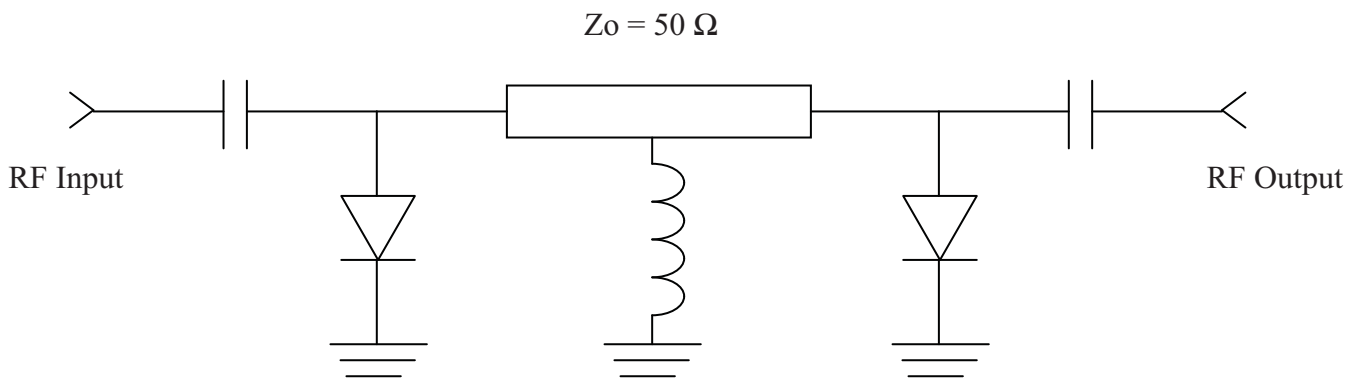
Absolute Maximum Ratings @ $T_A = + 25 \text{ }^\circ\text{C}$ (Unless Otherwise Defined)

| Parameter | Absolute Maximum Value |
|---|---|
| Operating Temperature | -65 °C to +125 °C |
| Storage Temperature | -65 °C to +150 °C |
| Junction Temperature | +175 °C |
| RF C.W. Incident Power @ + 85 °C Source & Load VSWR < 1.2:1 | +35 dBm |
| RF Peak. Incident Power @ + 85 °C Source & Load VSWR < 1.2:1 | + 50 dBm, RF Pulse Width = 1µS, 0.001 duty cycle |
| Insertion Loss Rate of Change with Operating Temperature | - 0.0025 dB / ° C |
| Assembly Temperature | +260 °C for 10 Seconds |

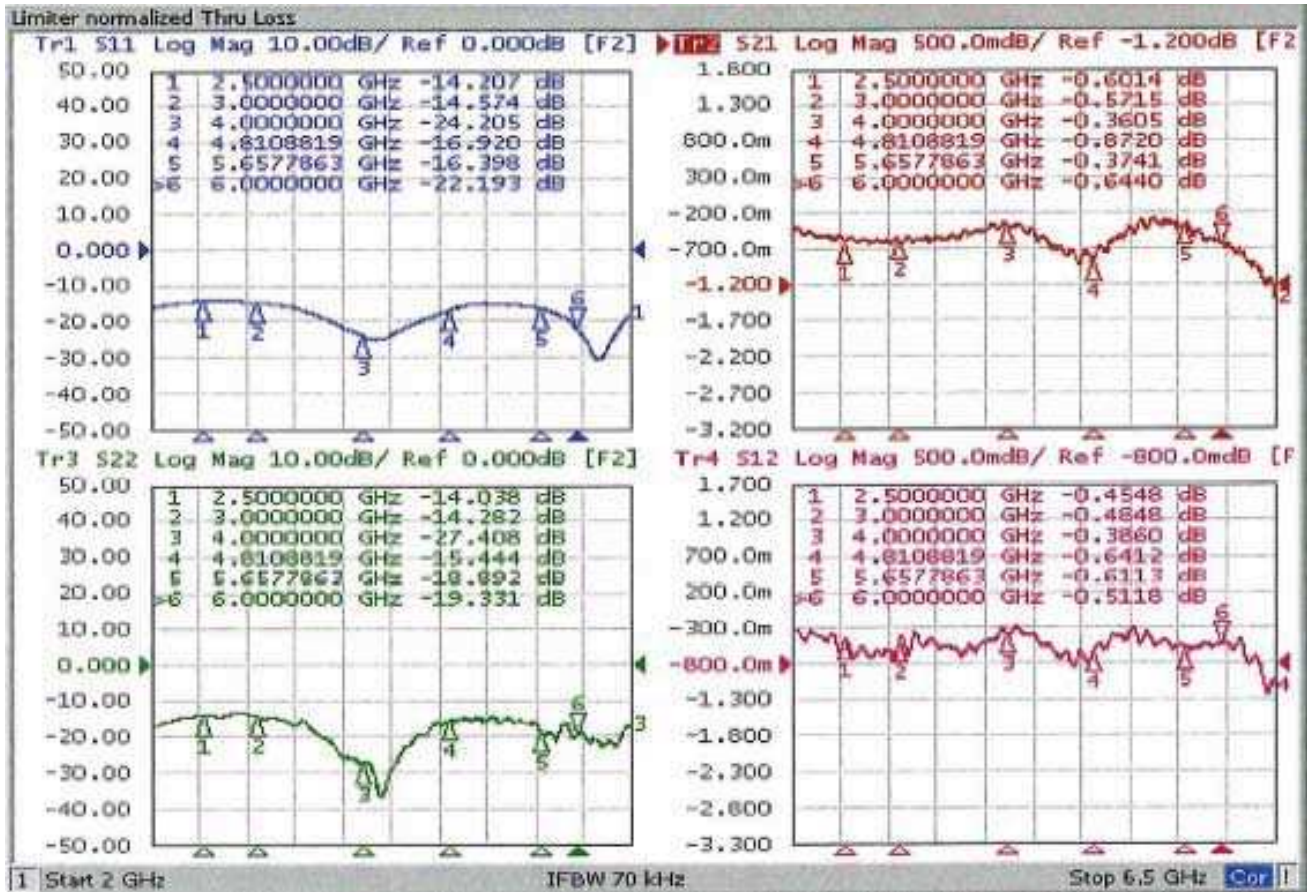
MLM2060-300 Limiter Schematic



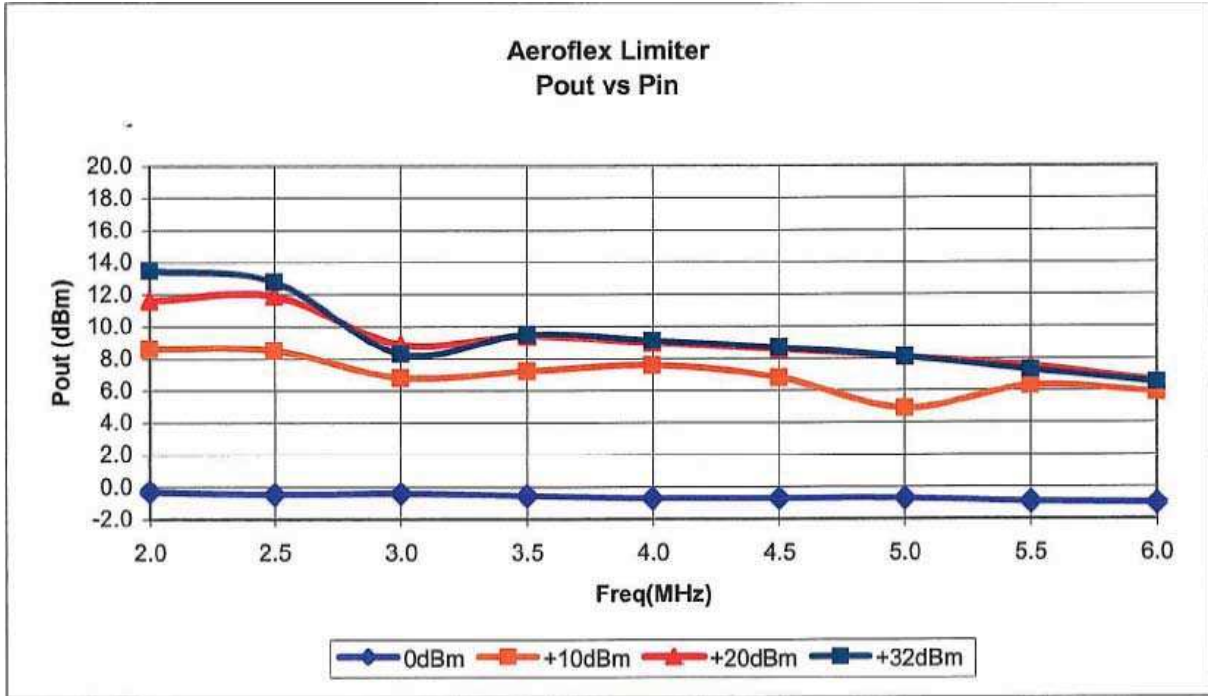
MLM2060-301 Limiter Schematic



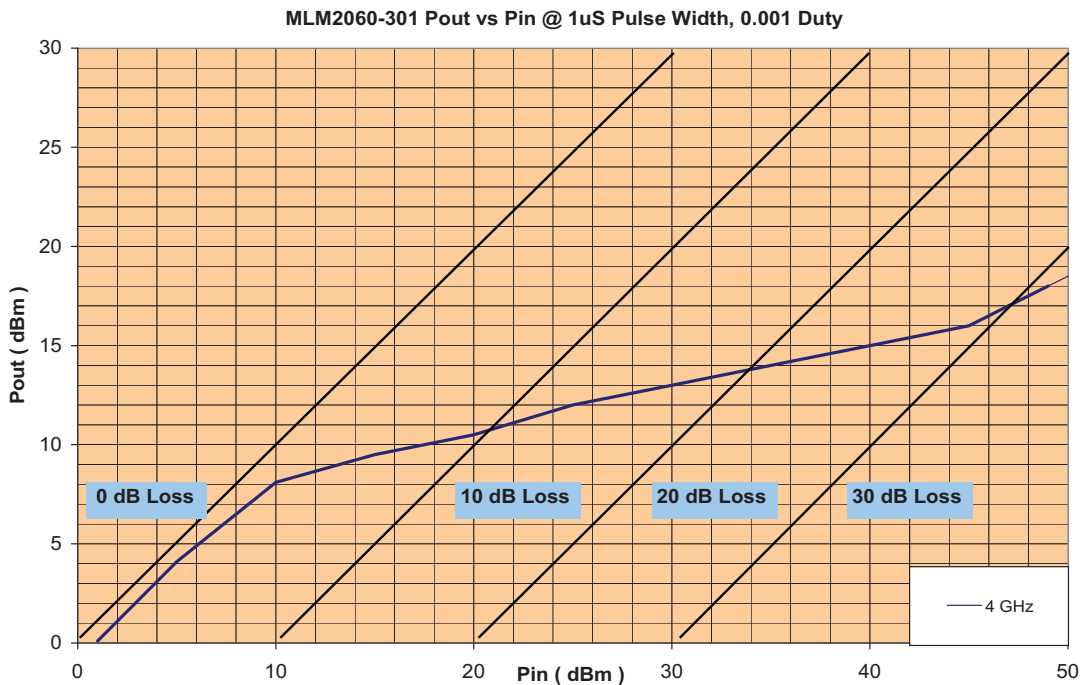
MLM2060-300 Typical RF Small Signal Performance @ +25 °C



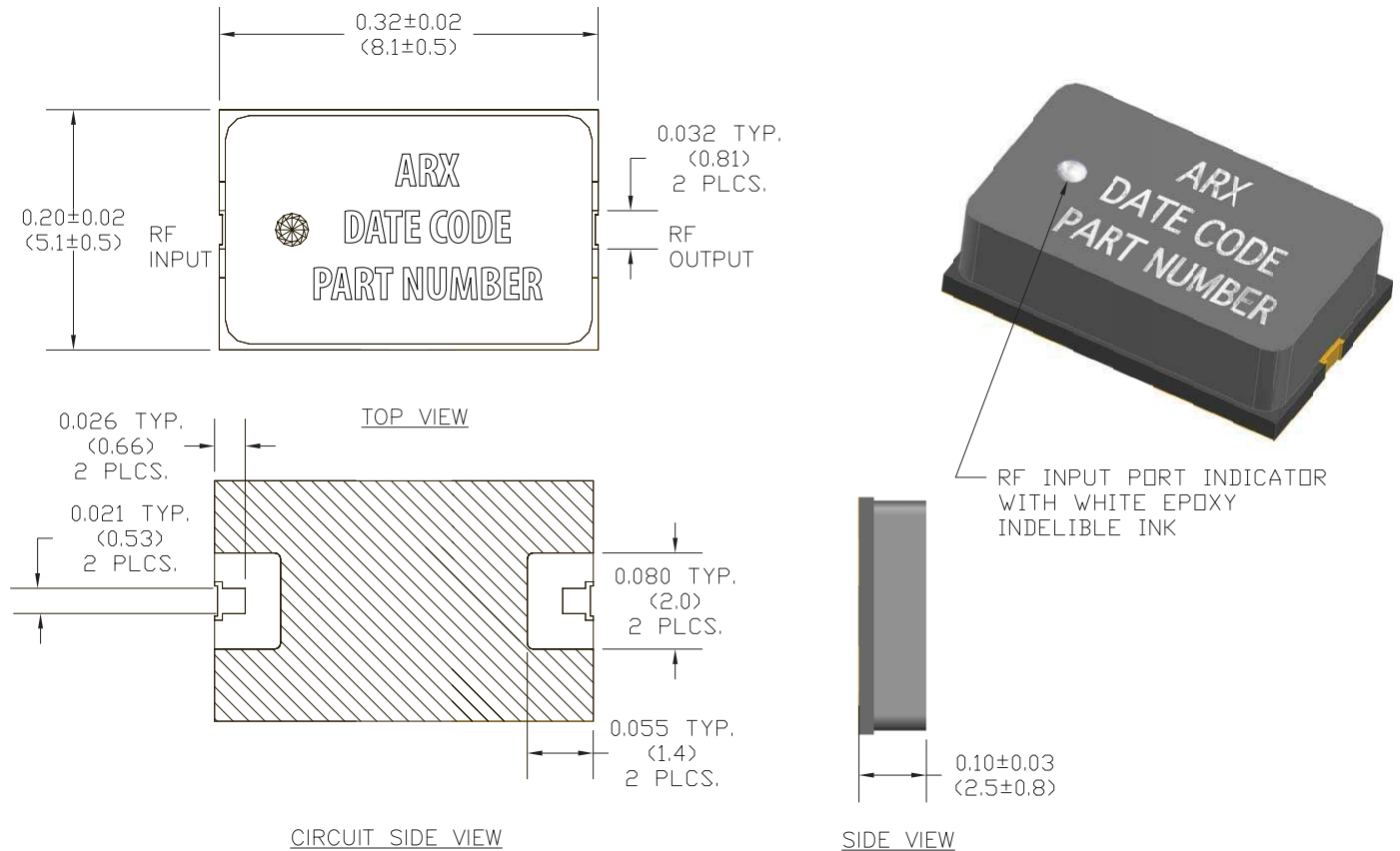
MLM2060-300 Typical RF C.W. Incident Performance @ +25 °C



MLM2060-301 Typical RF Peak Incident Power Performance @ +25 °C



MLM2060-300 Outline Drawing, Case Style 300, (CS300)

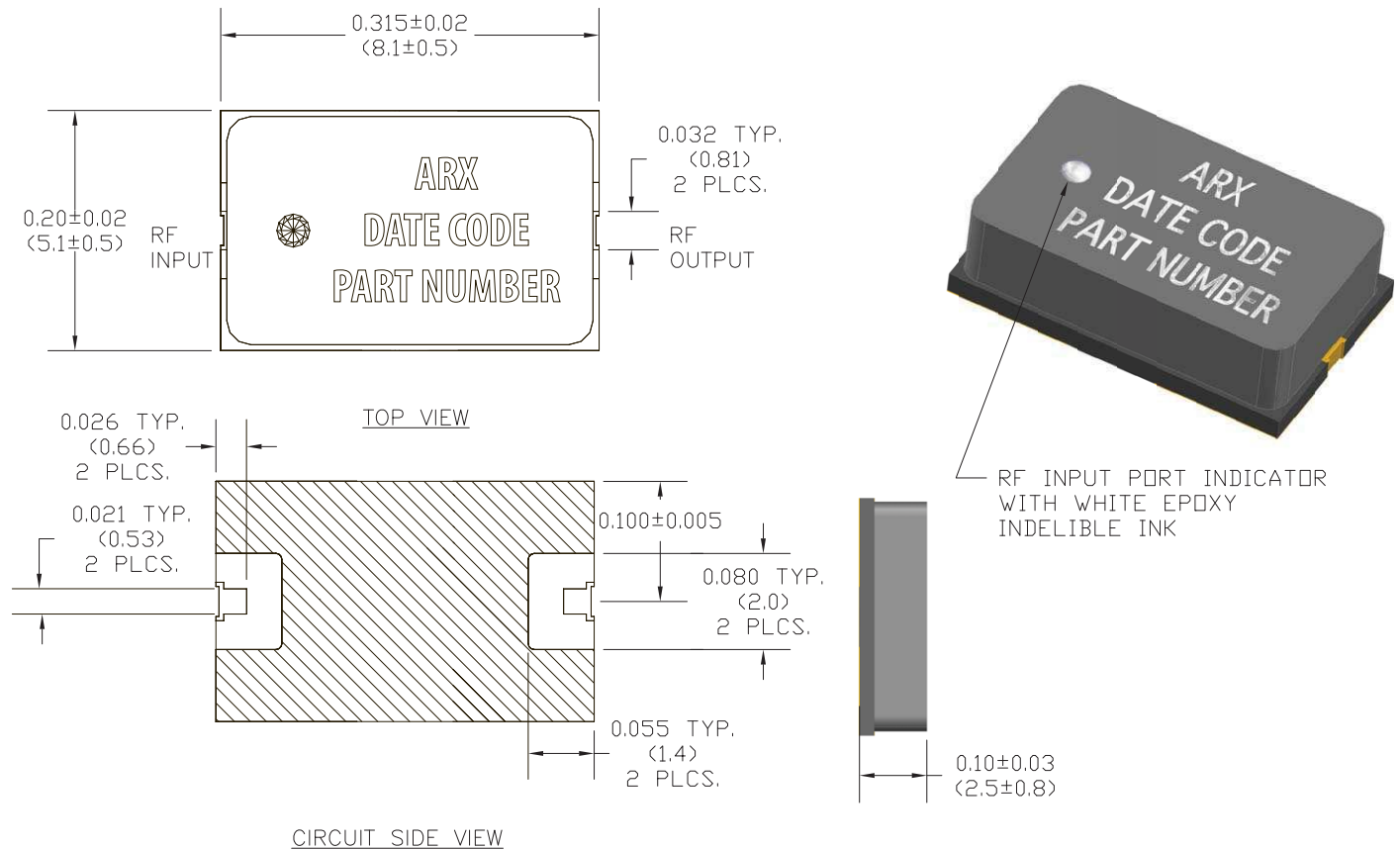


NOTES:

1. SUBSTRATE MATERIAL: 20 MIL THICK
ALUMINA NITRIDE (ALN) RF COVER: BLACK
CERAMIC.
2. TOP SIDE AND BACKSIDE METALLIZATION:
100 μ IN. TYPICAL PLATED Au OVER
Ti-Pd.
3. DIMENSION IN PARENTHESIS ARE IN MM.

PIN Diode Limiters

MLM2060-301 Outline Drawing Case Style 301, (CS301)



NOTES:

1. SUBSTRATE MATERIAL: 20 MIL THICK
ALUMINA NITRIDE (ALN) RF COVER: BLACK
CERAMIC.
2. TOP SIDE AND BACKSIDE METALLIZATION:
100 μ IN. TYPICAL PLATED Au OVER
Ti-Pd.
3. DIMENSION IN PARENTHESIS ARE IN MM.

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ISO 9001:2000

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